

Operation: 卧贴式(D+S)防水结构 & 3.1Type-C 连接器(24PIN)



ITEM NO.:MC-313FD (Consumer Electronics)

(L10.35×W10.30×H5.35mm & TYPE-C-SOCKETS)

1 Type-C CONNECTORS

邀您使用(微信)小程序

硕方电子开关&连接器选型手册

手机扫码即可进入...

Technical parameter

外焊贴片式 SMT

侧向导入 LATERAL

精密部品 NICETY

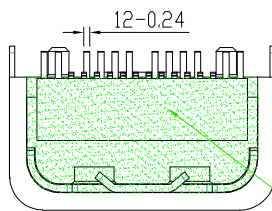
可靠 STABILIZE

环保材质 RoHS

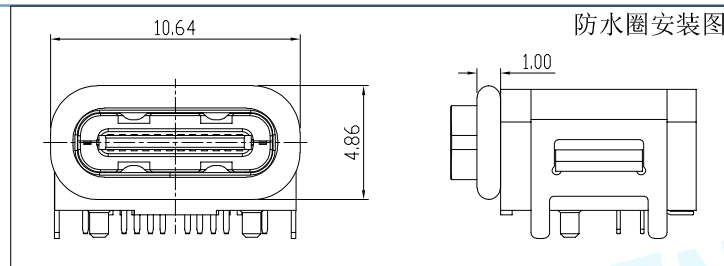
PROJECT	LEVEL	A[better product]		B[average product]	
Electrical Properties	Contact Rating	5A, 24V DC			
	Initial Contact Resistance	30mΩ max.		50mΩ max.	
	Insulation Resistance	100MΩ min.500V DC	Skey/PD:	100MΩ min.300V DC	
	Withstand Voltage	500V AC for 1 minute		350 V AC for 1 minut	
Durable Performance	There No Load	6,500 Cycles		5,500 Cycles	
	Rated Load	5,500 Cycles		4,500 Cycles	
	Storage Temp	25℃/50℃RH (Operating temperature: -35℃～+75℃)			

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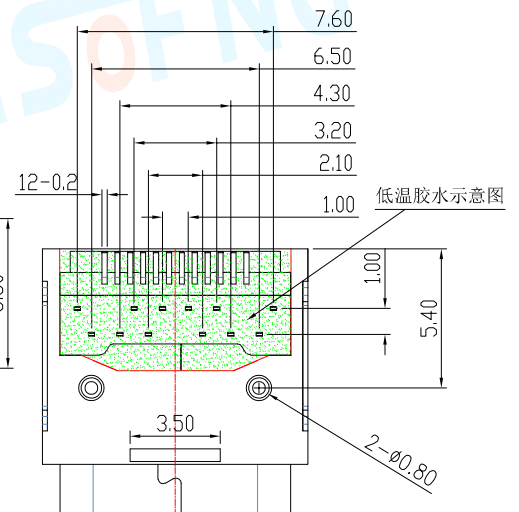
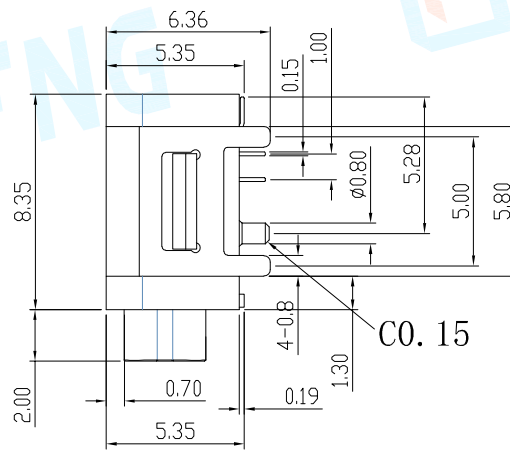
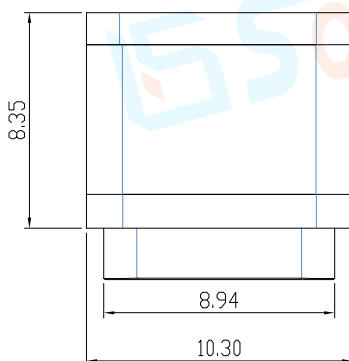
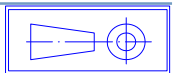
Unit:mm



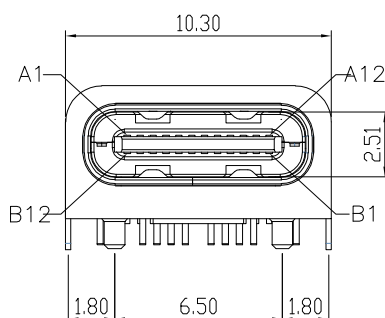
低温胶水示意图



防水圈安装图



低温胶水示意图



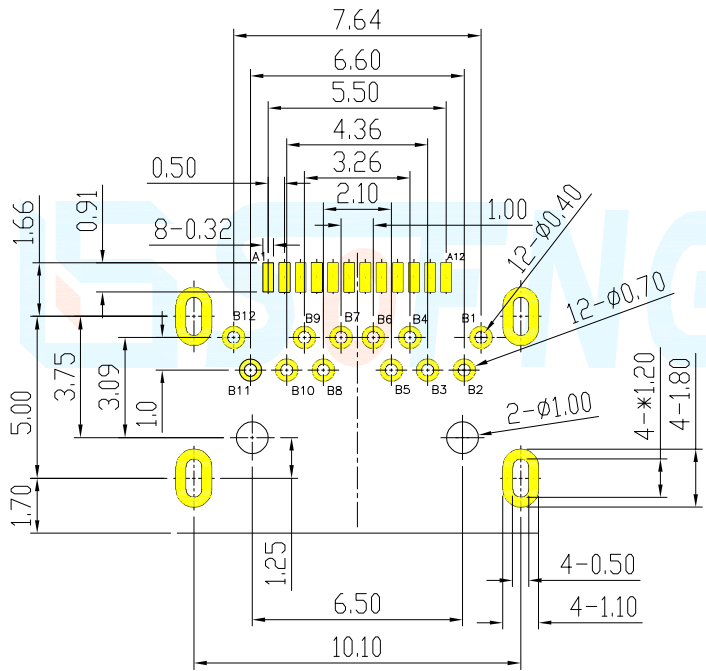
Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μm Ni PLATED OVERALL 0.25 μm Au PLATED CONTACT AREA GOLD FLASH ON SOLDER AREA
② B	HOUSING 基座	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
③ C	SHIELDING PLATE 屏蔽壳	STAINLESS STEEL	【G/F】0.25 μm Ni PLATED OVERALL;
④ D	SHELL 外壳	STAINLESS STEEL	【G/F】0.25 μm Ni PLATED OVERALL;
⑤ E	GND RING 接地件	STAINLESS STEEL	STAINLESS STEEL;
⑥ F	GLUE WATER 低温胶水	-	EPOXY[Black]



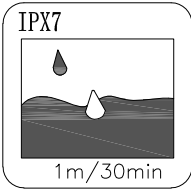
CIRCUIT BOARD SIZE
(Vertical view)

Operating Force	Inward	8. 0~20. 0N. (1N. =100gram-force)	Solder-ability (Max.)	IR Reflow: 255℃, 5sec.	Manual : 350℃, 3sec.
	Exiting	8. 0~20. 0N. (1N. =100gram-force)			



DECIMALS		ANGLES	
.X	:±0.25	X.°	:±1.5°
.XX	:±0.15	X.X°	:±1.0°
.XXX	:±0.10	.XXX°	:±0.5°

PIN ASSIGNMENTS



PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return

注記 NOTICE

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